

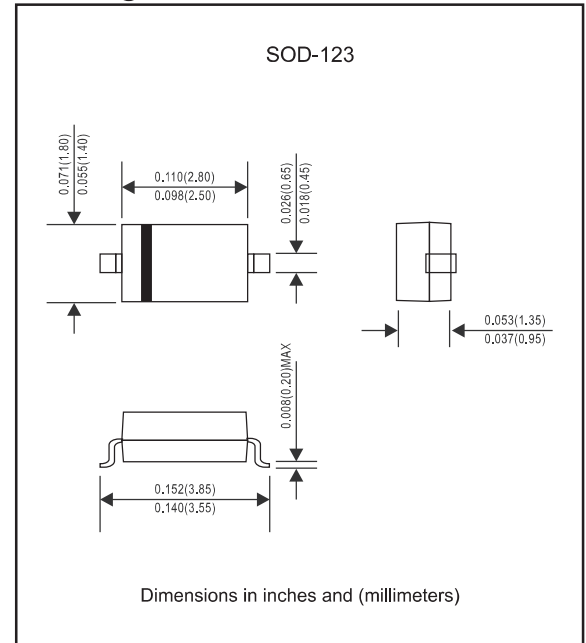
### Features

- Silicon epitaxial planar chip structure.
- Zener Breakdown Voltage Range, 2.4V to 43V ex.BZT52B2V4
- Small package size for high density applications.
- Ideally suited for automated assembly processes.
- Pb-Free package is available.
- Compliant to Halogen-free

### Mechanical data

- Epoxy : UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-123
- Terminals :Plated terminals, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any

### Package outline



### Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward voltage	@ $I_F = 10\text{mA}$	$V_F$			0.9	V
Total power dissipation	at $T_A=25^\circ\text{C}$ note1	$P_D$			500	mW
Thermal resistance	Junction to ambient, note1 Junction to case, note1	$R_{\theta JA}$ $R_{\theta JC}$		305 200		$^\circ\text{C/W}$ $^\circ\text{C/W}$
Operating junction temperature range		$T_J$	-55		+150	$^\circ\text{C}$
Storage temperature range		$T_{STG}$	-55		+150	$^\circ\text{C}$

Note1. Device mounted on ceramic PCB; 7.6mm x 9.4mm x 0.87mm with pad area 25mm<sup>2</sup>

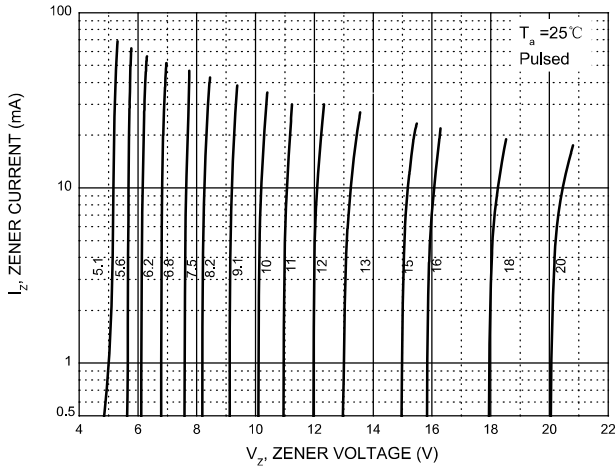
### Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Type Number	Type Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 3)			Maximum Reverse Current		Typical Temperature Coefficient @ $I_{ZTC}$		Test Current $I_{ZTC}$
		$V_Z@I_{ZT}$			$I_{ZT}$	$Z_{ZT}@I_{ZT}$	$Z_{ZK}@I_{ZK}$	$I_{ZK}$	$I_R$	$V_R$	mV/ $^\circ\text{C}$		
		Nom(V)	Min(V)	Max(V)	mA	$\Omega$		mA	$\mu\text{A}$	V	Min	Max	
BZT52B2V4	2WX	2.4	2.35	2.45	5	100	600	1.0	50	1.0	-3.5	0	5
BZT52B2V7	2W1	2.7	2.65	2.75	5	100	600	1.0	20	1.0	-3.5	0	5
BZT52B3V0	2W2	3.0	2.94	3.06	5	95	600	1.0	10	1.0	-3.5	0	5
BZT52B3V3	2W3	3.3	3.23	3.37	5	95	600	1.0	5	1.0	-3.5	0	5
BZT52B3V6	2W4	3.6	3.53	3.67	5	90	600	1.0	5	1.0	-3.5	0	5
BZT52B3V9	2W5	3.9	3.82	3.98	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52B4V3	2W6	4.3	4.21	4.39	5	90	600	1.0	3	1.0	-3.5	0	5
BZT52B4V7	2W7	4.7	4.61	4.79	5	80	500	1.0	3	2.0	-3.5	0.2	5
BZT52B5V1	2W8	5.1	5.00	5.20	5	60	480	1.0	2	2.0	-2.7	1.2	5
BZT52B5V6	2W9	5.6	5.49	5.71	5	40	400	1.0	1	2.0	-2.0	2.5	5
BZT52B6V2	2WA	6.2	6.08	6.32	5	10	150	1.0	3	4.0	0.4	3.7	5
BZT52B6V8	2WB	6.8	6.66	6.94	5	15	80	1.0	2	4.0	1.2	4.5	5
BZT52B7V5	2WC	7.5	7.35	7.65	5	15	80	1.0	1	5.0	2.5	5.3	5
BZT52B8V2	2WD	8.2	8.04	8.36	5	15	80	1.0	0.7	5.0	3.2	6.2	5
BZT52B9V1	2WE	9.1	8.92	9.28	5	15	100	1.0	0.5	6.0	3.8	7.0	5
BZT52B10	2WF	10	9.80	10.20	5	20	150	1.0	0.2	7.0	4.5	8.0	5
BZT52B11	2WG	11	10.78	11.22	5	20	150	1.0	0.1	8.0	5.4	9.0	5
BZT52B12	2WH	12	11.76	12.24	5	25	150	1.0	0.1	8.0	6.0	10.0	5
BZT52B13	2WI	13	12.74	13.26	5	30	170	1.0	0.1	8.0	7.0	11.0	5
BZT52B15	2WJ	15	14.70	15.30	5	30	200	1.0	0.1	10.5	9.2	13.0	5
BZT52B16	2WK	16	15.68	16.32	5	40	200	1.0	0.1	11.2	10.4	14.0	5
BZT52B18	2WL	18	17.64	18.36	5	45	225	1.0	0.1	12.6	12.4	16.0	5
BZT52B20	2WM	20	19.60	20.40	5	55	225	1.0	0.1	14.0	14.4	18.0	5
BZT52B22	2WN	22	21.56	22.44	5	55	250	1.0	0.1	15.4	16.4	20.0	5
BZT52B24	2WO	24	23.52	24.48	5	70	250	1.0	0.1	16.8	18.4	22.0	5
BZT52B27	2WP	27	26.46	27.54	2	80	300	0.5	0.1	18.9	21.4	25.3	2
BZT52B30	2WQ	30	29.40	30.60	2	80	300	0.5	0.1	21.0	24.4	29.4	2
BZT52B33	2WR	33	32.34	33.66	2	80	325	0.5	0.1	23.1	27.4	33.4	2
BZT52B36	2WS	36	35.28	36.72	2	90	350	0.5	0.1	25.2	30.4	37.4	2
BZT52B39	2WT	39	38.22	39.78	2	130	350	0.5	0.1	27.3	33.4	41.2	2
BZT52B43	2WU	43	42.14	43.86	2	130	350	0.5	0.1	29.4	36.4	45.2	2

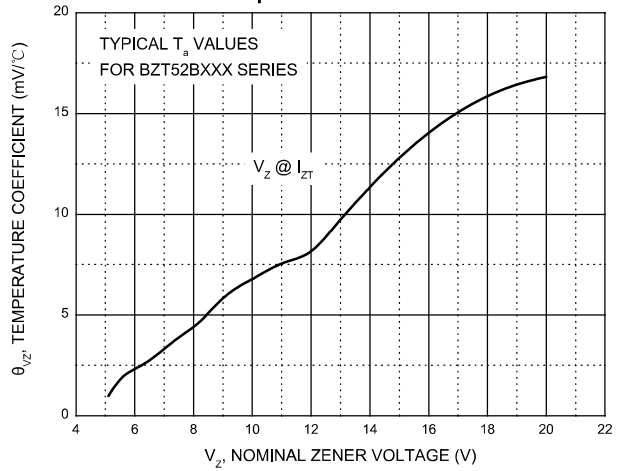
Notes: 1. Device mounted on ceramic PCB:7.6mm x 9.4mm x 0.87mm with pad areas 25mm<sup>2</sup>  
 2. Short duration test pulse used to minimize self-heating effect  
 3 f = 1kHz

## Rating and characteristic curves (BZT52B Series)

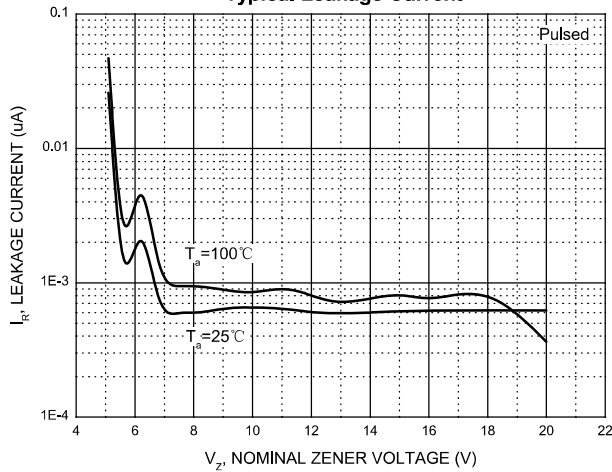
**Zener Characteristics ( $V_z$  5.1V to 20 V)**



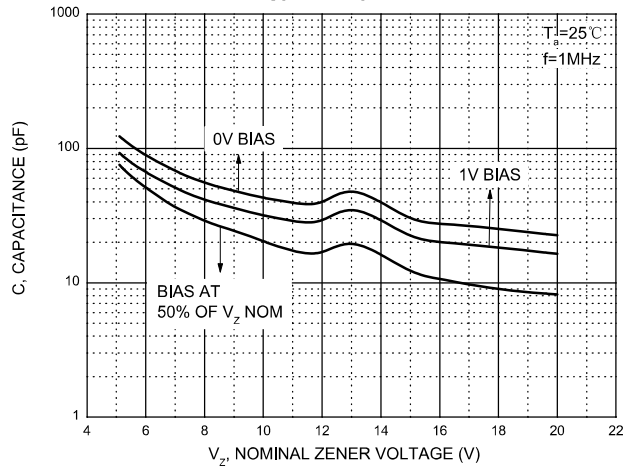
**Temperature Coefficients**



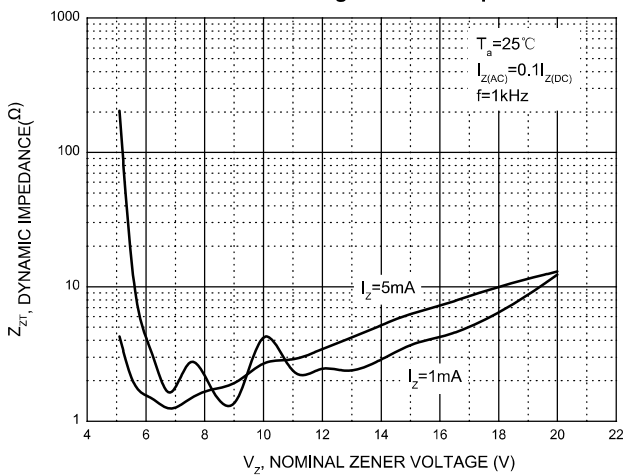
**Typical Leakage Current**



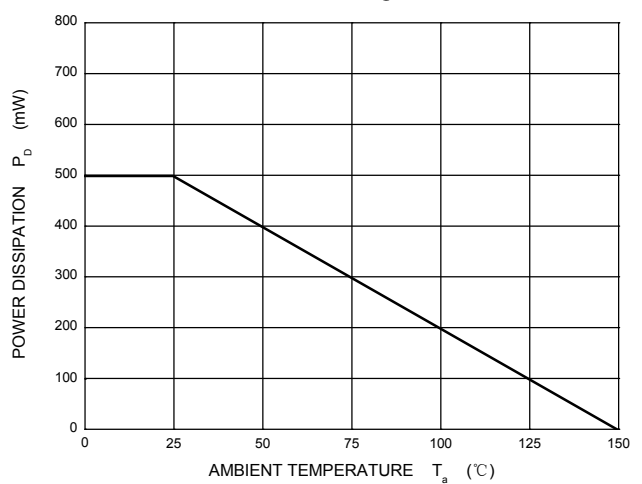
**Typical Capacitance**





**Effect of Zener Voltage on Zener Impedance**



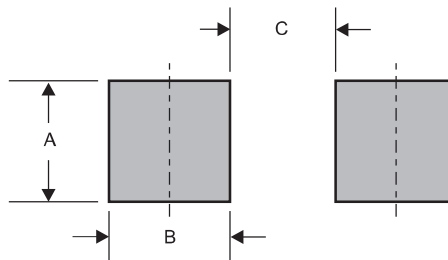
**Power Derating Curve**



## Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

## Suggested solder pad layout



Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-123	0.048 (1.22)	0.036 (0.91)	0.093 (2.36)